



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDM-1001	REV: E2	SUN REV: Not In VersionControl
	TID #: TIDM-1001		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 2/23/2017	11:37:42 PM	TEXAS INSTRUMENTS

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